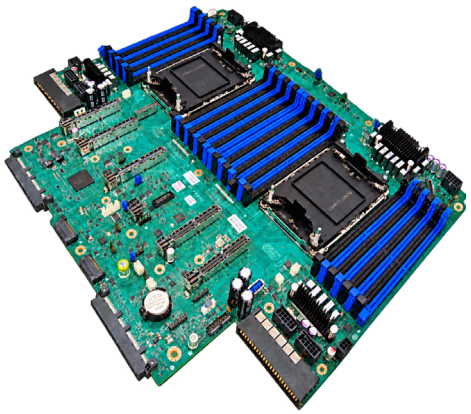
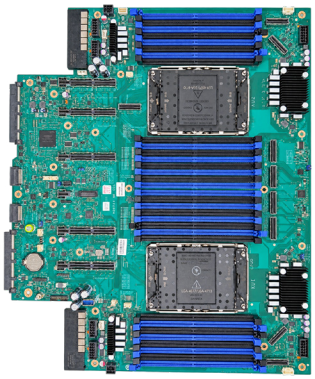




Hyve-Designed Motherboard Gen 2: HS9224-I

Featuring Dual-Socket Intel® Xeon® 6 Processors with P-cores

Built for virtualization, databases, analytics, and high-I/O data services that benefit from dual-socket compute, memory capacity, and dense PCIe Gen5 expansion. Based on the OCP DC-MHS FLW architecture, this HPM deploys across Hyve Solutions Axis™ 1U and 2U platforms.

Key Features

- Dual-Socket / Intel Xeon 6 Processors with P-cores up to 350W
- DC-MHS FLW / 423mm x 348mm
- 32 DDR5 DIMM Slots / 8 Memory Channels / 64GB / 96GB DIMM Configuration
- 9x PCIe Gen5 x16 Expansion Slots / 144 PCIe Lanes
- 2x E1.S Boot Drive Supported
- 1x OCP3.0 Gen5 x16 NIC
- DC-SCM 2.0 HFF / AST2600 / AST1060 RoT / TPM 2.0 Management / AMI BIOS 64MB

Board Specifications

Form Factor / Dimensions	DC-MHS FLW / 423mm x 348mm
CPU Socket / Supported Processors	LGA4710 / Intel Xeon 6 Processor Family / 2 Socket
Expansion Slots / PCIe	9x PCIe Gen5 x16 Slots, Capable of x2, x4, x8, and x16 Bifurcation
Memory	32 DIMM Slot / DDR5 DIMM / 5200 MT/s (2DPC) / 64GB / 96GB Capacity
Storage Interfaces	2x E1.S 9.5mm Boot Devices Supported (M.2 Interposer)
Networking / LAN	1x OCP 3.0 Gen5 x16 NIC
Rear I/O Panel	1x USB 3.1/2.0 Type A (DC-SCM) 1x UART Connector (DC-SCM) 1x RJ45 Dedicated LAN (DC-SCM)

Fan Headers / Thermal Sensors	4056/ 6056 Fan Supported (Fan Board)
System Management	DC-SCM 2.0 HFF/ AST2600 / OpenBMC
Security / TPM	Aspeed AST1060 RoT / TPM2.0 (DC-SCM)
Power Connectors	2x 3000W CRPS / MCRPS PSU
BIOS / Firmware	AMI BIOS / 64MB
Operating Environment	5°~35°C

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